DEPARTMENT OF DEFENSE
UNITED STATES OF AMERICA

DEFENSE LOGISTICS AGENCY
DEFENSE SUPPLY CENTER, COLUMBUS
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IN REPLY REFER TO DSCC-VQ (VQE-07-13789/Mr. Werman/614-692-0631/wew) June 29, 2007

SUBJECT: Notification of Qualification, MIL-PRF-31032 / MIL-PRF-55110, CAGE Code: 66311

Mr. Robert Lageman
Unicircuit Inc.
8192 Southpark Lane
Littleton, CO 80120

Dear Mr. Lageman:

Qualification of your products is granted under the current issue of the specifications as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1 and MIL-PRF-31032/2. The material and classification indicated below shall be listed on Qualified Manufacturers List QML-31032. Additionally, qualification is granted to QPL-55110 per paragraph 6.3.4 of MIL-PRF-31032 and MIL-PRF-55110 Appendix B. The effective date of these qualifications is June 29, 2007.

MANUFACTURER NAME & ADDRESS	BASIC PLANT LOCATION	CAGE CODE: 66311
Unicircuit Inc. 8192 Southpark Lane Littleton, CO 80120	SAME	CONTACT: Bob Lageman PHONE#: 303-730-0505 X110 EMAIL: blageman@unicircuit.com

CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE: MIL-PRF-31032 /1, /2		QUALIFICATION LETTERS:
Base Materials	GI (Woven E-Glass, Polyimide resin)	VQE-07-13789
Max. Panel Size	12” X 18”	
Max. Board Thickness	0.120”	
Min/Max Drilled thru-hole	0.020” / 0.129”	
Laser Via Hole Size	0.006 +/- 0.001	
Aspect Ratio	6 : 1	
Max Number of Layers	16	
Min. Conductor Width	0.005”	
Min. Conductor Spacing	0.005”	
Part Mounting	SMT, THM	
Finish Systems	Hot Air Solder Level (HASL), Reflowed Tin Lead	
Hole Preparation	Plasma Etchback	
Copper Plating	Electrodeposited Acid Copper	
Solder Resist	Liquid Photoimageable (LPI)	
Alternate Construction	Sequential Lamination, Blind and Buried Via, Laser-drilled Microvias, Foil Lamination	
Controlled Impedance	55 ohms characteristic, 100 ohms differential impedance +/- 10%	

This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.

2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.

3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.

4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.

5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Since we are held responsible for the accuracy and currency of this QML, please inform us if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Bill Werman at bill.werman@dla.mil or (614) 692-0631.

Sincerely,

ROBERT P. EVANS
Chief
Sourcing and Qualification Unit